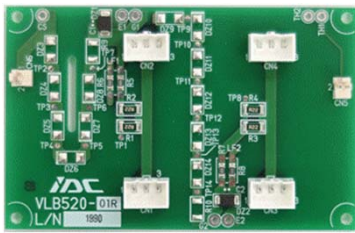


VLB520-01R



FEATURES

- >Directly mountable on the IGBT module (thin DUAL type)
- >Easy and flexible to use for gate parallel connection
- >Built in Total Line length Adjustment Circuit (TLAC) for gate parallel connection
- >Wire connection to gate driver unit
- >Built-in connector for thermistor

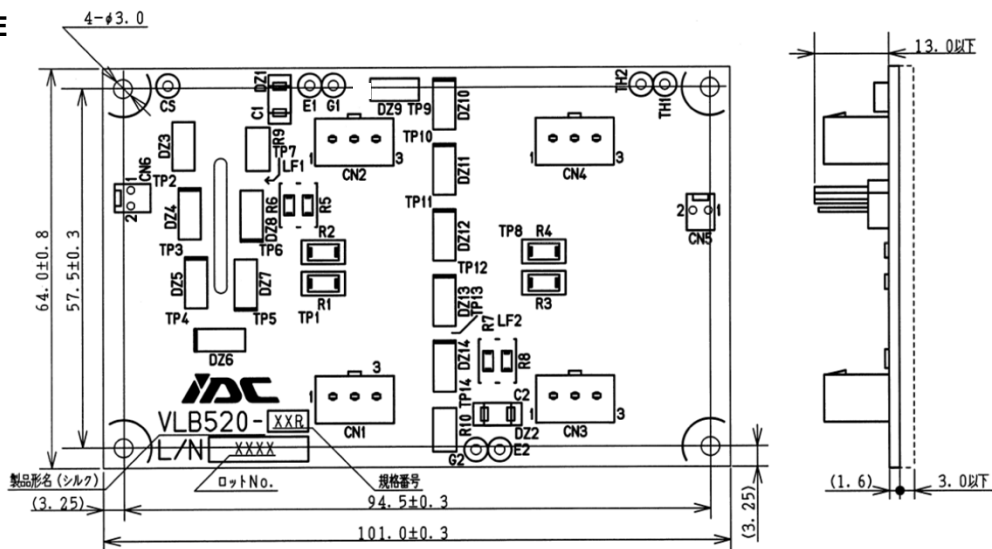
TARGETED IGBT MODULES

VCES=1200V/1700V series up to 800A class thin DUAL type

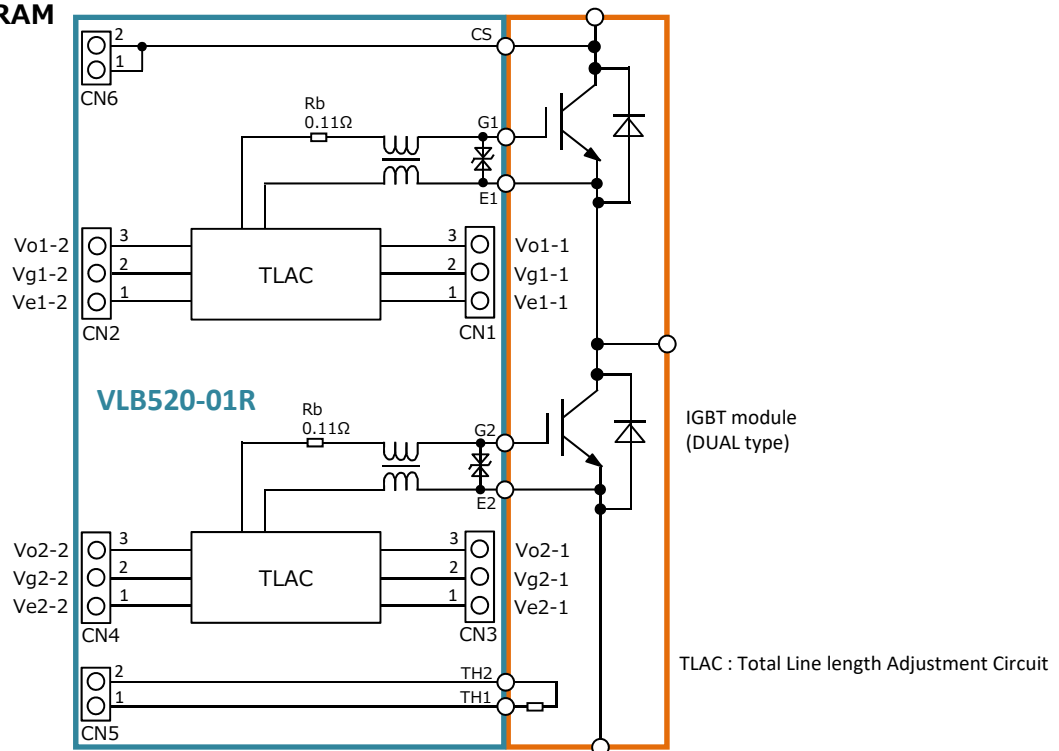
APPLICATIONS

Inverter, Servo, UPS, Solar power or Wind power etc.

OUTLINE



BLOCK DIAGRAM



MAXIMUM RATINGS

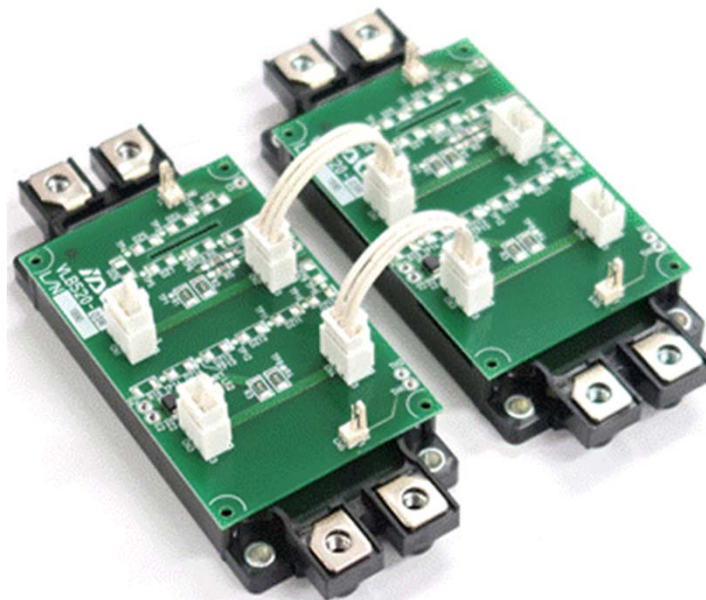
(unless otherwise noted, Ta=25 °C)

Symbol	Parameter	Conditions	Ratings	Unit
Topr	Operating temperature	No condensation allowable	-40 ~ 85	deg C
Tstg	Storage temperature	No condensation allowable	-40 ~ 85	deg C
Pd_rb	Maximum power dissipation of balance resistor	Total value of 2 chip resistors per 1circuit	1.2	W
VDC_Link	Main circuit voltage	The supply voltage of main circuit	1500	V
VCp	Collector peak voltage	Peak voltage on CS terminal	2000	V

ELECTRICAL CHARACTERISTICS

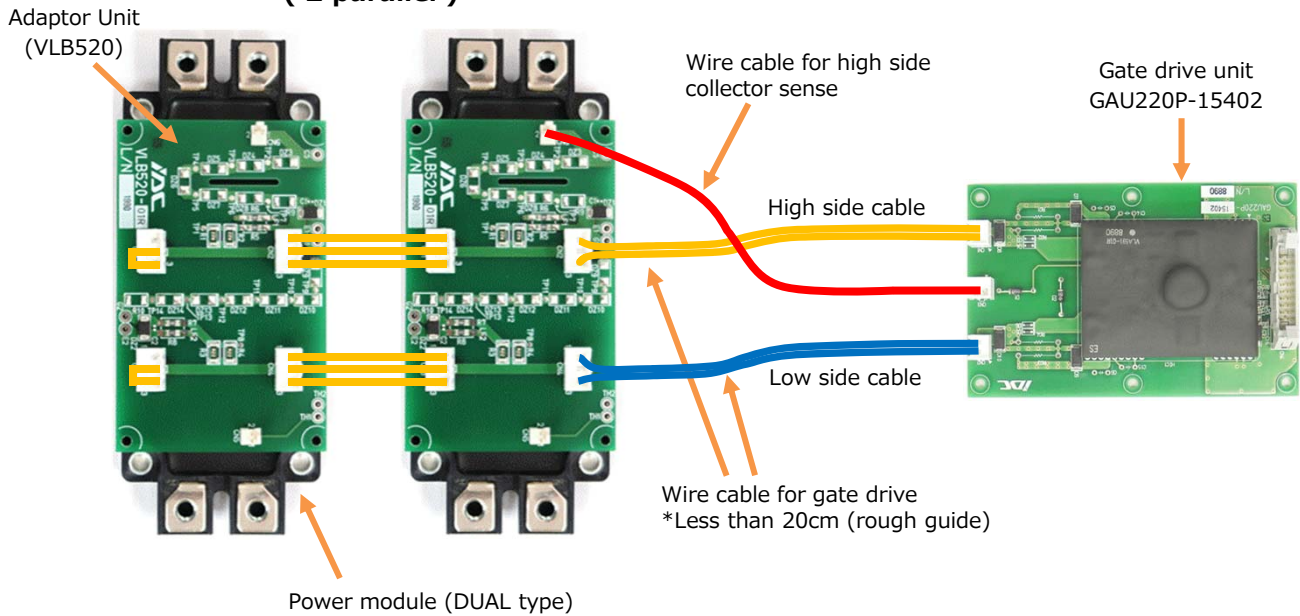
(unless otherwise noted, Ta=25°C)

Symbol	Item	Conditions	Limits			Unit
			Min	Typ	Max	
Rb	Balance resistance	Compound value of 2 chip resistors per 1circuit	-	0.11	-	Ω



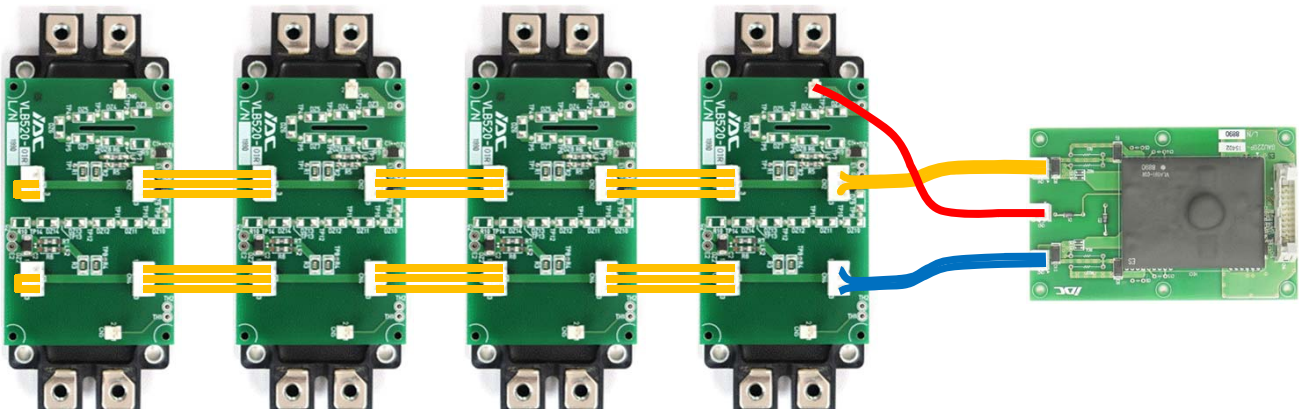
CONNECTION EXAMPLE

(2 parallel)



Note) When gate drive cable exceeds 20cm, please make it a twisted pair.

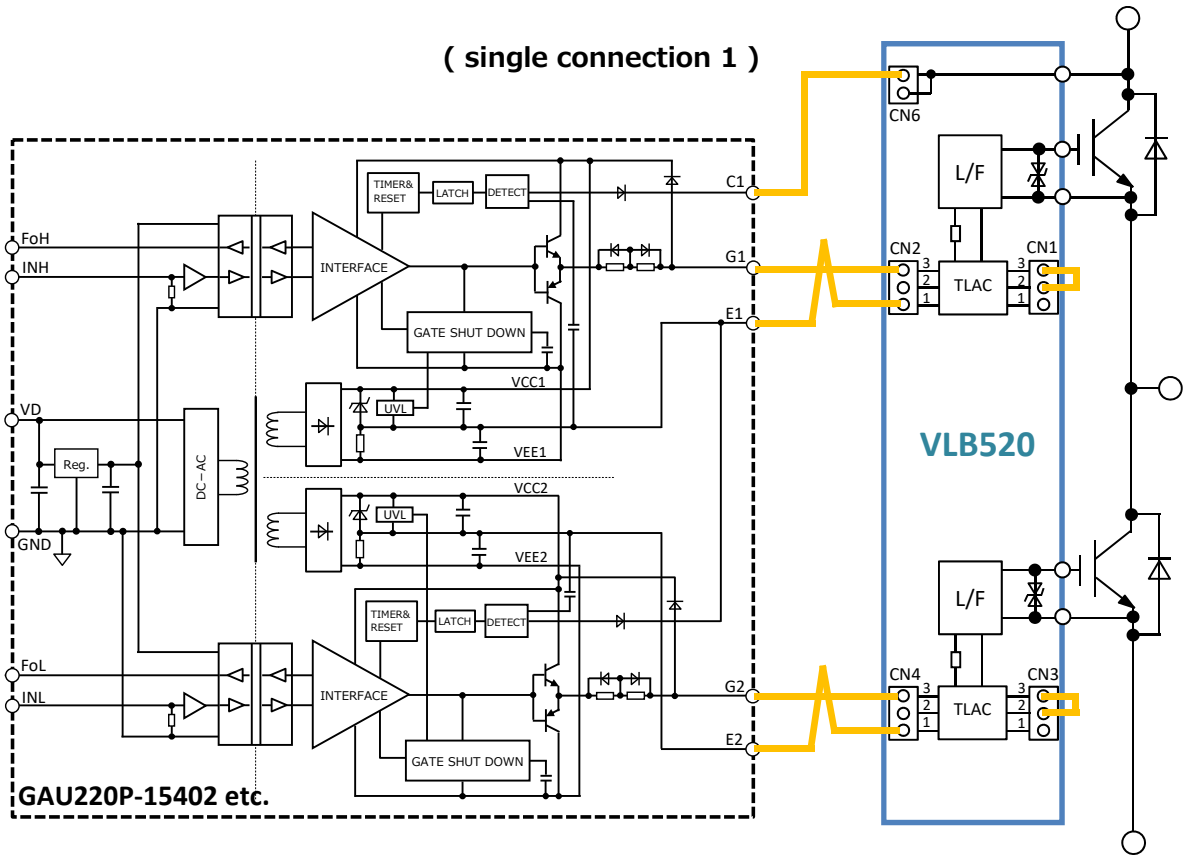
(4 parallel)



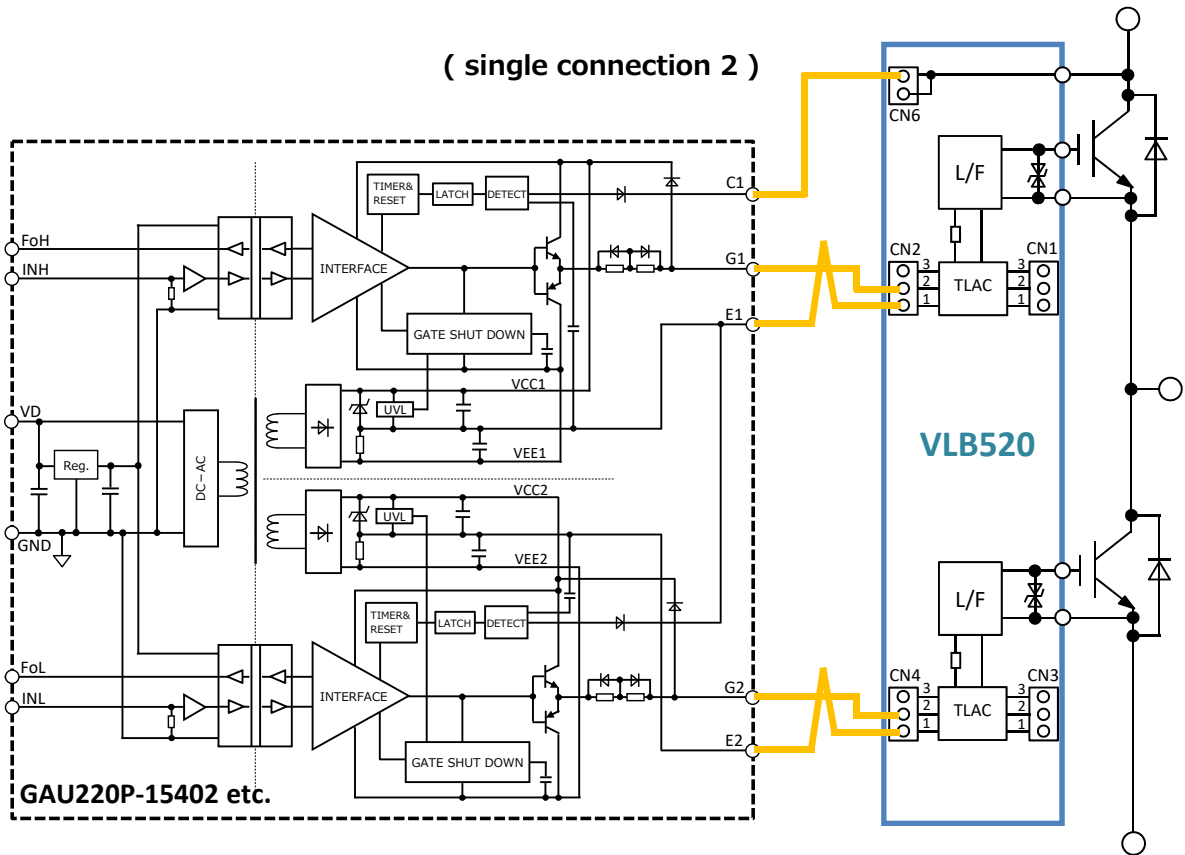
Note) The harness for connections doesn't attach at the time of shipment.

APPLICATION EXAMPLE1

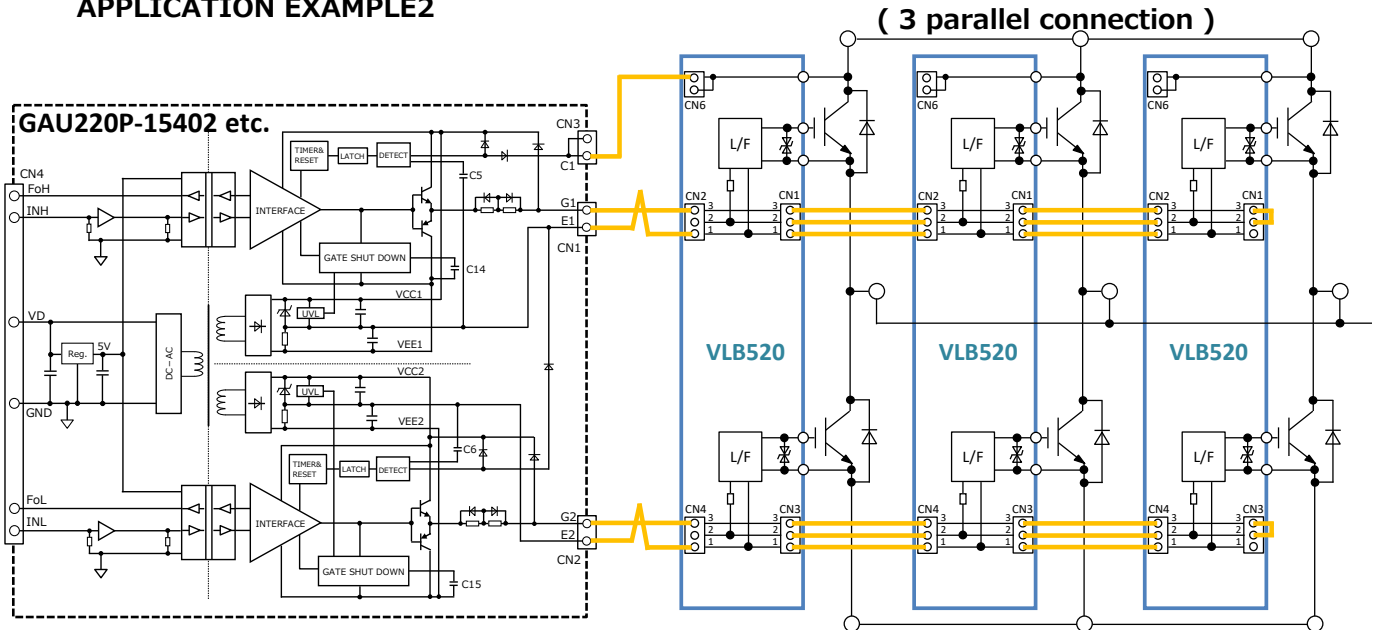
(single connection 1)



(single connection 2)



APPLICATION EXAMPLE2



THE WAY TO CALCULATE GATE RESISTANCE VALUE OF PARALLEL CONNECTION

$RG_ON/1elem. = \text{Gate ON resistance value per one element} = R_b + (N \times Rg_on)$

$RG_OFF/1elem. = \text{Gate OFF resistance value per one element} = R_b + (N \times Rg_off)$

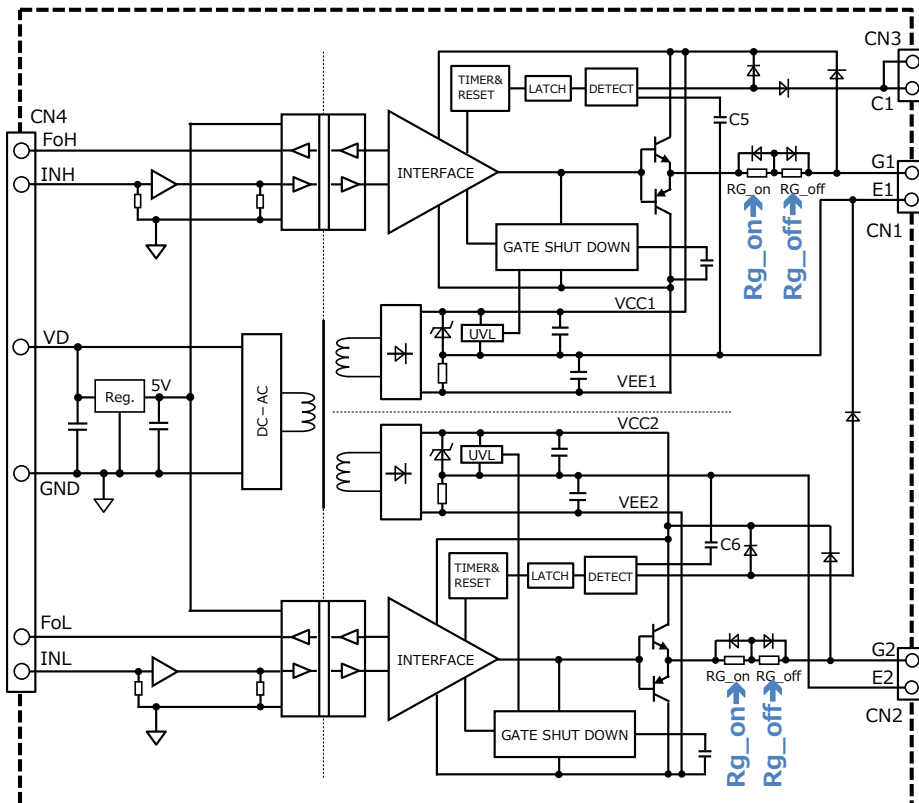
Note) R_b : 0.11Ω (Compound value of 2 chip resistors on VLB520-01R)

N : Parallel number of modules

Rg_on : Gate ON resistance value on gate drive unit

Rg_off : Gate OFF resistance value on gate drive unit

Gate drive unit (Ex. GAU220P-15402)



DETAILS OF CONNECTOR

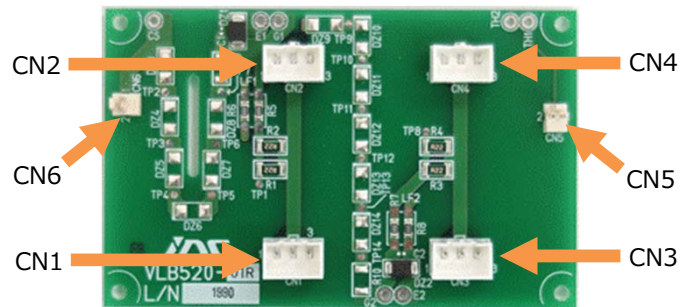
CN1: 53258-0329 (Molex)	
Pin No.	Signal
1	Ve1-1
2	Vg1-1
3	Vo1-1

CN5: 5045-02A (Molex)	
Pin No.	Signal
1	TH1
2	TH2

CN2: 53258-0329 (Molex)	
Pin No.	Signal
1	Ve1-2
2	Vg1-2
3	Vo1-2

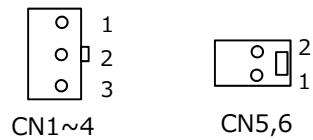
CN6: 5045-02A (Molex)	
Pin No.	Signal
1	CS
2	CS

CN3: 53258-0329 (Molex)	
Pin No.	Signal
1	Ve2-1
2	Vg2-1
3	Vo2-1



CN4: 53258-0329 (Molex)	
Pin No.	Signal
1	Ve2-2
2	Vg2-2
3	Vo2-2

Pin No. assignment of connector

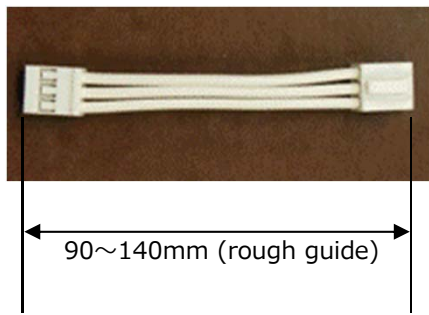
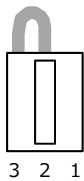
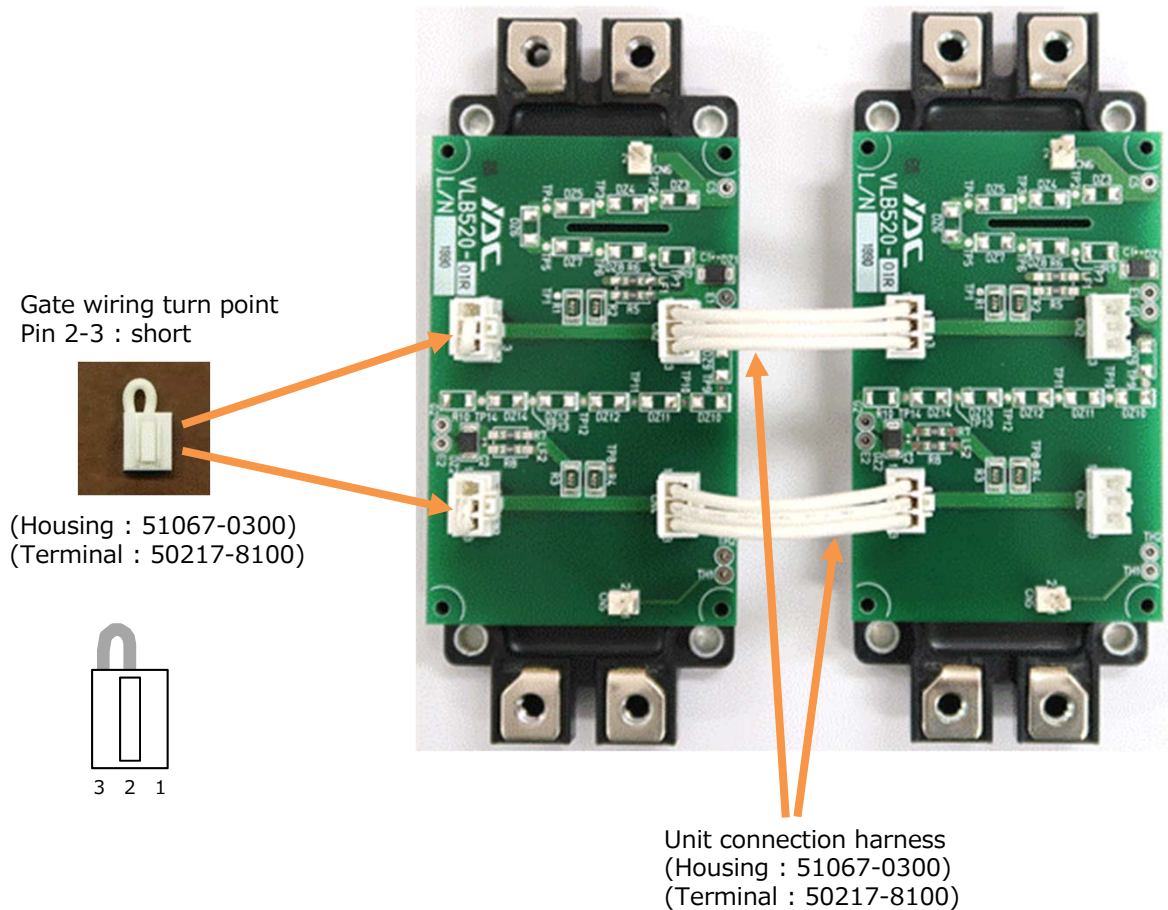


We recommend following parts or equivalent product for wire cable

HOUSING	TERMINAL	Maker	Note
51067-0300	50217-8100	Molex	to 53258-0329
5051-02	5159	Molex	to 5045-02A

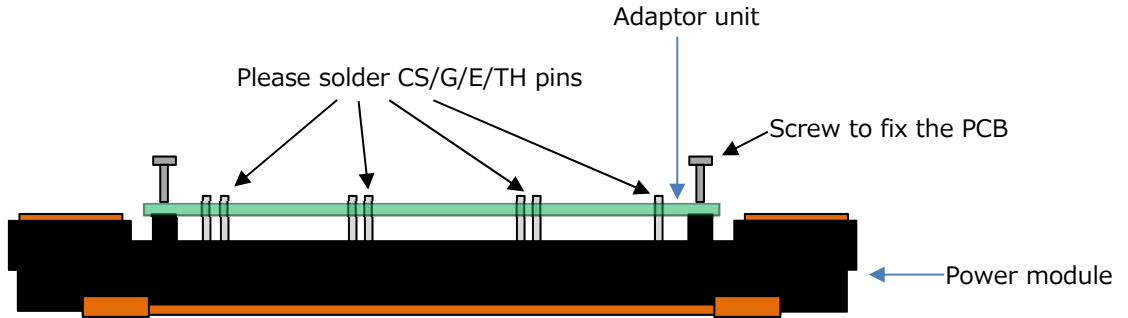
HARNESS FOR PARALLEL CONNECTION

The harness for connections doesn't attach at the time of shipment, please prepare the harness like following figure.



- Note**
- 1) Please make the length of 3 lines the same length about the unit connection harness.
 - 2) When 3 lines of harness become dispersive, please take a measure by an spiral tube or insulok etc.

THE INSTALLATION OF THE ADAPTOR UNIT ON POWER MODULE



Note) Temperature of soldering iron tip : 360°C (max) under 5 seconds



PRELIMINARY

VLB520-01R

ADAPTOR FOR GATE PARALLEL CONNECTION

FOR SAFETY USING

Great detail and careful attention are given to the production activity of Hics, such as the development, the quality of production, and in it's reliability. However the reliability of Hics depends not only on their own factors but also in their condition of usage. When handling Hics, please note the following cautions.

CAUTIONS	
Packing	The materials used in packing Hics can only withstand normal external conditions. When exposed to outside shocks, rain and certain environmental contaminators, the packing materials will deteriorates. Please take care in handling.
Carrying	<ol style="list-style-type: none"> 1) Don't stack boxes too high. Avoid placing heavy materials on boxes. 2) Boxes must be positioned correctly during transportation to avoid breakage. 3) Don't throw or drop boxes. 4) Keep boxes dry. Avoid rain or snow. 5) Minimal vibration and shock during transportation is desirable.
Storage	<p>When storing Hics, please observe the following notices or possible deterioration of their electrical characteristics, risk of solder ability, and external damage may occur.</p> <ol style="list-style-type: none"> 1) Devices must be stored where fluctuation of temperature and humidity is minimal, and must not be exposed to direct sunlight. Store at the normal temperature of 5 to 30 degrees Celsius with humidity at 40 to 60%. 2) Avoid locations where corrosive gasses are generated or where much dust accumulates. 3) Storage cases must be static proof. 4) Avoid putting weight on boxes.
Extended storage	When extended storage is necessary, Hics must be kept non-processed. When using Hics which have been stored for more than one year or under severe conditions, be sure to check that the exterior is free from flaw and other damages.
Maximum ratings	To prevent any electrical damages, use Hics within the maximum ratings. The temperature, current, voltage, etc. must not exceed these conditions.
Polarity	To protect Hics from destruction and deterioration due to wrong insertion, make sure of polarity in inserting leads into the board holes, conforming to the external view for the terminal arrangement.

Keep safety first in your circuit designs!

·ISAHAYA Electronics Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (1) placement of substitutive, auxiliary circuits, (2) use of non-flammable material or (3) prevention against any malfunction or mishap.

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